

## PATENT ABSTRACTS OF JAPAN

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(71)Applicant : COPAL CO LTD

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### (54) ELECTRICALLY CONDUCTIVE COMPOSITION

#### (57)Abstract:

PURPOSE: To provide an electrically conductive compsn. which has excellent solderability and tensile strength and gives thick-coating Cu paste which does not cause deterioration in characteristics by heat during soldering, containing Cu powder, glass frit and V2O5.

CONSTITUTION: 90W97.5wt% Cu powder having a particle size of 0.3W1.5 $\mu$ m, 1.5W2.0wt% glass frit (e.g. lead borosilicate glass) having a softening point of 250W400°C, which contains at least 50wt% PbO blended therewith, 1W6wt% V2O5 having a particle size of 2 $\mu$ m or below and optionally, dispersant and anti-foaming agent are mixed together to obtain an electrically conductive compsn. 12W16pts.wt. org. vehicle is mixed with 100pts.wt. compsn. The resulting electrically conductive paste is applied to a substrate by screen printing, dried and fired at a peak temp. of 830W950°C.